

SV2080A

Density Optimized 2U 4-node Server
to Address Growing Computing Needs



High-reliable Network Connectivity

The standard-compliant OCP 3.0 slot enables installation of a NIC to provide high bandwidth and ultra-low latency for server networking, and features tool-less design for easy serviceability.

High-density Computing in a Compact Design

Equipped with four independent nodes, the server delivers unprecedented performance to handle complex workloads in a small chassis, making it a great choice to increase compute density in limited spaces.

Hybrid Storage Configurations

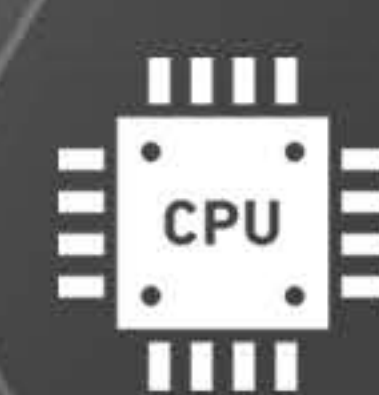
To satisfy different user scenarios, the server supports various storage configurations: (1) 12 x 2.5"/3.5" SATA (2) 24 x 2.5" NVMe (3) 12 x 2.5" NVMe/3.5" SATA for maximum flexibility. An optional U.2 NVMe SSD can also be installed on the rear for greater storage expansion.

High-speed PCIe Expansion Capability

Supporting PCIe Gen4, the product offers a superior bandwidth of 16 GT/s, double the speed of PCIe Gen3, to enable faster data transfer rate for versatile I/O options.

Application

- Hexagon icon: Hyperscale Data Center
- Hexagon icon: Database
- Hexagon icon: Software-defined Storage
- Hexagon icon: Hyper-converged Infrastructure
- Hexagon icon: Enterprise Application Server



8 x 3rd Generation
AMD EPYC™
Processors



64 x DDR4 RDIMM/
LRDIMM



2.5"/3.5"
SATA/NVMe Drives



1+1 Redundancy,
Platinum Level



2U Rackmount

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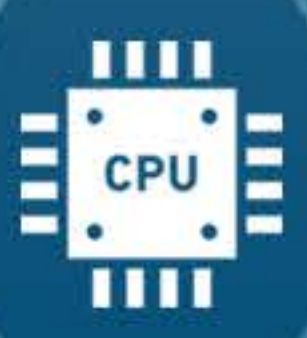
Specifications



North America: +1 408-727-8060



Email: Sales@ingrasys.com



Processor

One/Two* 2nd/3rd Generation AMD EPYC™ Processor(s), up to 32 Cores, 180W (TDP) per Node
*SKU 1: One Processor, SKU 2 & 3: Two Processors



Memory

16 x DDR4 3200MHz RDIMM/LRDIMM per Node, 1 x NVDIMM per Node



Storage

Front

SKU 1: 12 x 2.5"/3.5" Hot-swap SATA Drives per Chassis (3 x Drives per Node)
SKU 2: 24 x 2.5" Hot-swap U.2 NVMe Drives per Chassis (6 x Drives per Node)
SKU 3: 12 x 3.5" Hot-swap SATA or 2.5" Hot-swap NVMe Drives per Chassis (3 x Drives per Node)

Internal

1 x SATA/NVMe M.2 (2280/22110) per Node
1 x SATA M.2 (2280/22110) per Node

Rear

1 x 2.5" Hot-swap 7/15mm U.2 NVMe SSD per Node
(Optional for Single Processor Configuration, Occupy One PCIe LP Slot)



Front Panel (per Node)

1 x Power Button with LED
1 x UID Button with LED
1 x System Health LED



Rear Panel (per Node)

1 x RJ45 for BMC Dedicated Management
1 x VGA
2 x USB 3.0
1 x UID Button with LED



TPM

1 x TPM 2.0 Module per Node



Expansion Slots

Up to 2 x PCIe Gen4 x16 LP Slots per Node (by SKU)
1 x OCP 3.0 NIC PCIe Gen4 x16 per Node



Management

1 x ASPEED AST2500 BMC per Node
Support Intelligent Platform Management Interface v.2.0



PSUs

1+1 Redundant 3000W Platinum PSU (2200W for Single Processor Configuration)



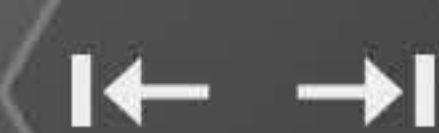
Fans

3 x 40*56mm per Node, 12 x per Chassis



Certification

FCC/CE/UL/CB



Chassis Dimensions (H x W x D)

3.42" x 17.6" x 33.17" /
87.0mm x 447.0mm x 842.4mm



Operating Temperature

5°C to 35°C (41°F to 95°F)

Non-operating Temperature

-40°C to 70°C (-40°F to 158°F)

Operating Relative Humidity

8% to 90%RH

Non-operating Relative Humidity

5% to 90%RH



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